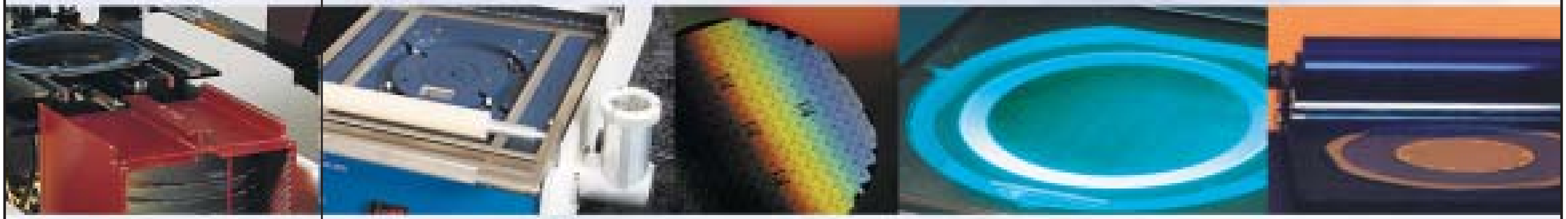

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Controlled Tape Tensioning for Optimal Wafer Dicing

1. Dicing tape tension is programmable to mount wafers providing optimal dicing conditions.
2. Dicing tape application under vacuum prevents air-bubble formation, especially important for small-die applications.
3. Gentle mounting process provides safe and reliable mounting of delicate and mechanically sensitive wafers.
4. Provides an unequalled solution for the mounting of uneven surfaced substrates.
5. Excess tape is accurately and safely trimmed on the frame using automatic trimmers.
6. Static eliminator option removes electrical charges from dicing tape. ESD wrist-strap socket protects devices during the mounting process.
7. UV curable dicing tape is easily applied using the UV tape backing removal option.
8. A controlled-temperature platen provides optimal tape application conditions for standard dicing tape.
9. Special-design chucks are available to accommodate all wafer/frame/tape combinations, up to 8”.

VWM-871 Options

1. UV tape backing remover - ejects UV tape backing from system to facilitate process waste material management.
2. ESD eliminator - ionizer bar eliminates electrostatic charges on mounting tape to protect ESD-sensitive devices.
3. Custom-designed work surfaces to accommodate specific application requirements.

Technical Specifications

Electrical utility:	110/240 Vac, 50/60 Hz	
Power:	500 W (max.)	
Dimensions:	61” (H) x 20.4” (W) x 33.5” (D)	155 (H) x 52 (W) x 85 cm (D)
Air:	72 p.s.i., c.d.a.	5 bar
Weight:	220 lbs.	100 kg

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VWM-871 Vacuum Wafer Mounting System

General Description

AE's VWM-871 implements innovative process technology by mounting wafers and other substrates in a vacuum environment. Proper tape tensioning and bubble-free mounting are critical elements for consistent, reliable dicing and singulation results. The VWM-871 provides fully adjustable tape tensioning and air-bubble free mounting results, due to its advanced PLC-controlled vacuum tape application system. The VWM-871 accurately mounts all standard wafer and film frame sizes up to 8”.

A Cost Effective, Easy-to-Operate System

With its small footprint and built-in vacuum generator, the VWM-871 is a highly sophisticated system, requiring minimal workspace and utilities. Simple to set up and operate, the VWM-871 wafer mounting process is accurate, controlled and repeatable, with minimal operator intervention. Excess dicing tape is cut and trimmed safely and automatically. With its piston-aided cover-lifting mechanism and ergonomic design, operators find the VWM-871 easy-to-use throughout their shift. Robust mechanical design means reliable wafer mounting, day-in and day-out. Requiring only compressed air and electricity, the compact-sized VWM-871 can be installed in any convenient location in the plant.

VWM-871 Features-at-a-Glance

- Air-Bubble Free Tape Mounting.
- Controlled, Programmable Tape Tension.
- No Mechanical Contact with Substrate During Mounting.
- Safe, Simple, Accurate Operation.
- Easy-to-Use Touch Screen Operator Interface.
- Compact Small-Footprint Design.
- Built-in Vacuum Generator.
- Closed-loop, Digital Platen Temperature Control.
- Chuck Accommodates All Standard Wafer/Film Frame Sizes, Up to 8".
- Static Eliminator Option.
- UV Tape Option.